THE INVENTION CLAIMED IS:

1. A multichip module package, comprising:

a first heat sink positioned for releasing heat from the package;

a second heat sink positioned proximate the first heat sink wherein the heat sinks are planar in two substantially parallel planes;

means thermally coupling and electrically isolating the heat sinks to and from one another;

a first semiconductor device attached to the first heat sink in thermal and electrical communication therewith and electrically insulated from the second heat sink; and

a second semiconductor device attached to the second heat sink in thermal and electrical communication therewith and electrically insulated from the first heat sink.

2. The package of claim 1:

further comprising:

a substrate attached to the second heat sink on the side thereof opposite the first heat sink; and

electrical circuitry on the substrate on the side thereof opposite the second heat sink;

and wherein:

the semiconductor devices are electrically connected to the electrical circuitry.

3. The package of claim 1 further comprising an electrically conductive epoxy electrically connecting the semiconductor devices to their respective heat sinks.

~~4. The package of claim 1 wherein the heat sinks are planar in two substantially parallel planes.~~

~~5~~4. The package of claim 1 wherein the package is configured for applying different electrical potentials respectively to the first heat sink and to the second heat sink.

~~6~~5. A multichip module package, comprising:

a first heat sink positioned for releasing heat from the package;

a second heat sink positioned beneath the first heat sink;

means thermally coupling and electrically isolating the heat sinks to and from one another;

a substrate attached to the second heat sink on the side thereof opposite the first heat sink;

a first semiconductor device attached to the first heat sink through and in thermal and electrical communication therewith and electrically insulated from the second heat sink;

a second semiconductor device attached to the second heat sink in thermal and electrical communication therewith and electrically insulated from the first heat sink; and

an encapsulant environmentally encapsulating the first and second semiconductor devices.

~~7~~6. The package of claim ~~6~~5 further comprising electrical circuitry on the substrate opposite the second heat sink, and wherein the semiconductor devices are electrically connected to the electrical circuitry.

~~8~~7. The package of claim ~~6~~5 further comprising an electrically conductive epoxy electrically connecting the semiconductor devices to their respective heat sinks.

~~9~~8. The package of claim ~~6~~5 wherein the heat sinks are planar in two substantially parallel planes.

~~10~~9. The package of claim ~~6~~5 wherein the package is configured for applying different electrical potentials respectively to the first heat sink and to the second heat sink.